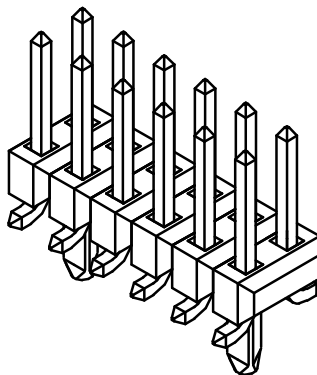




PRODUCT SPECIFICATION



SERIES 71308

C-GRID® SMT .100" GRID DUAL ROW HEADERS SERIES 71308

- 1.0 SCOPE
- 2.0 PRODUCT DESCRIPTION
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D4	EC No: UCP2013-0050 DATE: 2012/07/09	.100" GRID VERTICAL DUAL ROW SURFACE MOUNT HEADERS	1 of 3
DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
PS-71308	MMSTROH	MKIPPER	FSMITH



PRODUCT SPECIFICATION

1.0 SCOPE:

This specification covers C-Grid® dual row surface mount headers. They utilize a gull wing design for surface mounting. The mating pins are .025in (0.64mm) square on a .100in (2.54mm) grid.

2.0 PRODUCT DESCRIPTION:

2.1 PRODUCT NAME AND SERIES NUMBER(S)

2.1.1 SERIES 71308: Low profile vertical surface mount header.

DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

C-Grid® series 71308 is available in circuit sizes of 4 through 100 circuits and is end to end stackable. The wafer is made from glass filled Liquid Crystal Polymer, (LCP) having a UL 94V-0 flammability rating. Mating pin lengths are .240in (6.0mm), and .320in (8.1mm) with gold or tin plating. Integral mounting pegs are offered in two lengths for each series as an option to aid assembly and/or retention during soldering. For further details, refer to sales document in section 3.1.

2.2 SAFETY AGENCY APPROVALS

2.2.1 UNDERWRITERS' LABORATORIES (UL) FILE NUMBER: E29179

2.2.2 CANADIAN STANDARDS ASSOCIATION (CSA) FILE NUMBER: LR19980

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

3.1 MOLEX DOCUMENTS

SD--71308-001 SALES DRAWING FOR LOW PROFILE C-GRID® SMT HEADER
PK-70873-0353 PACKAGING SPECIFICATION FOR BULK PACKAGED PRODUCT (CIRCUIT SIZES 4-8)
PK-70873-0041 PACKAGING SPECIFICATION FOR TUBE PACKAGED PRODUCT (CIRCUIT SIZES 10-80)
PK-70873-0691 PACKAGING SPECIFICATION FOR TUBE PACKAGED PRODUCT WITH PICK AND PLACE CAPS
PK-70873-0805 PACKAGING SPECIFICATION FOR TAPE AND REEL PRODUCT WITH PICK AND PLACE CAPS
PS-45499-002 COSMETIC SPECIFICATION

3.2 OTHER DOCUMENTS

MIL STD 202F

4.0 RATINGS

4.1 VOLTAGE: 250 Volts DC

4.2 CURRENT: 3.0 Amps (DC) max

4.3 TEMPERATURE

4.3.1 PROCESSING TEMPERATURE: 245°C max. intermittent for bright tin plating
260°C max. intermittent for select gold plating.

4.3.2 OPERATING TEMPERATURE: -40°C to +120°C

5.0 PERFORMANCE

5.1 ELECTRICAL REQUIREMENTS

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PRODUCT SPECIFICATION

- 5.1.1 INSULATION RESISTANCE: Greater than 1000M Ω
- 5.1.2 DIELECTRIC WITHSTANDING VOLTAGE: Greater than 600Volts at sea level.
- 5.1.3 TEMPERATURE RISE: 30°C max at rated current

5.2 MECHANICAL REQUIREMENTS

- 5.2.1 RETENTION PEGS (Optional Item)
 - 5.2.1.1 INSERTION FORCE: 8.0 lbs average per peg (.062in PCB hole)
 - 5.2.1.2 RETENTION FORCE: 4.0 lbs average per peg (.062in PCB hole)

5.3 ENVIRONMENTAL REQUIREMENTS

- 5.3.1 THERMAL SHOCK
 - 10 Cycles from -40°C to 105°C, ½ hour at each temperature setting.
- 5.3.2 CHEMICAL RESISTANCE
 - Per Mil. Std. 202F, Method 215A.

6.0 PACKAGING

Product is available in bulk pack, tube pack and tape and reel. Tape and reel packaging includes a pick-n-place cap, ideal for high volume robotic placement. The pick-n-place cap is optional for tube packaged product. Refer to section 3.1 for applicable packaging document.

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